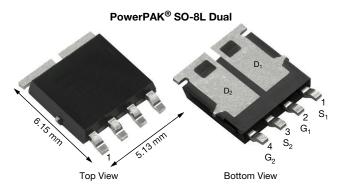
SQJB00EP

www.vishay.com

Vishay Siliconix

Automotive Dual N-Channel 60 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY	
V _{DS} (V)	60
$R_{DS(on)}\left(\Omega\right)$ at V_{GS} = 10 V	0.0130
I _D (A) per leg	30
Configuration	Dual

FEATURES

- TrenchFET[®] power MOSFET
- AEC-Q101 qualified
- 100 % R_q and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS COMPLIANT HALOGEN FREE

MMARY		
	60	G1 O1
10 V	0.0130	
	30	
	Dual	
		N-Chan

-		G2 0
	N-Channel MOSFET	N-Cha

D1

Q

 D_2

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SQJB00EP (for detailed order number please see <u>www.vishay.com/doc?79771</u>)

ABSOLUTE MAXIMUM RATING	S (T _C = 25 °C, unles	s otherwise noted)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source coltage		V _{DS}	60	V
Gate-source coltage		V _{GS}	± 20	v
Continuous drain current	T _C = 25 °C	1	30	
Continuous drain current	T _C = 125 °C	I _D	25	
Continuous source current (diode conduction) ^a Pulsed drain current ^b Single pulse avalanche current L = 0.1 mH		I _S	30	А
		I _{DM}	84	
		I _{AS}	23	
Single pulse avalanche energy		E _{AS}	26.5	mJ
Maximum power dissipation ^b	T _C = 25 °C	T _C = 25 °C 48	W	
maximum power dissipation ⁵	T _C = 125 °C	PD	16	vv
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +175	°C
Soldering recommendations (peak temperature) ^{d, e}			260	-0

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction to ambient	PCB mount ^c	R _{thJA}	85	°C/W
Junction to case (drain)		R _{thJC}	3.1	0/10

Notes

a. Package limited

b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %

c. When mounted on 1" square PCB (FR4 material)

d. See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

1

e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

S22-0060-Rev. B, 24-Jan-2022

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PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static				•	•	•	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 250 μA	60	-	-	v
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μΑ	2.5	3.0	3.5	v
Gate-Source Leakage	I _{GSS}	V _{DS} =	0 V, $V_{GS} = \pm 20$ V	-	-	± 100	nA
		$V_{GS} = 0 V$	V _{DS} = 60 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	$V_{DS} = 60 \text{ V}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	-	50	μA
		$V_{GS} = 0 V$	V _{DS} = 60 V, T _J = 175 °C	-	-	150	
On-State Drain Current ^a	I _{D(on)}	$V_{GS} = 10 V$	$V_{DS} \ge 5 V$	30	-	-	Α
		$V_{GS} = 10 V$	I _D = 10 A	-	0.0105	0.0130	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 10 \text{ V}$	I _D = 10 A, T _J = 125 °C	-	-	0.0208	Ω
		$V_{GS} = 10 V$	I _D = 10 A, T _J = 175 °C	-	-	0.0255	
Forward Transconductance b	9 _{fs}	V _{DS}	= 15 V, I _D = 10 A	-	36	-	S
Dynamic ^b	-						
Input Capacitance	C _{iss}			-	1300	1700	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	V _{DS} = 25 V, f = 1 MHz	-	550	750	pF
Reverse Transfer Capacitance	C _{rss}]		-	28	40	
Total Gate Charge ^c	Qg			-	20	35	
Gate-Source Charge ^c	Q _{gs}	$V_{GS} = 10 V$	$V_{DS} = 30 \text{ V}, \text{ I}_{D} = 1.5 \text{ A}$	-	6	-	nC
Gate-Drain Charge ^c	Q _{gd}]		-	3	-	
Gate Resistance	R _g		f = 1 MHz	0.25	0.51	0.80	Ω
Turn-On Delay Time ^c	t _{d(on)}			-	13	25	
Rise Time ^c	t _r	V _{DD} :	= 30 V, $R_1 = 20 \Omega$	-	3	10	
Turn-Off Delay Time ^c	t _{d(off)}		$V_{GEN} = 10 \text{ V}, \text{ R}_{g} = 1 \Omega$	-	23	40	ns
Fall Time ^c	t _f			-	22	40	
Source-Drain Diode Ratings and Chara	acteristics ^b	• •					
Pulsed Current ^a	I _{SM}			-	-	84	Α

Notes

f. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %.

g. Guaranteed by design, not subject to production testing.

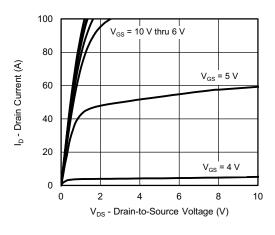
h. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

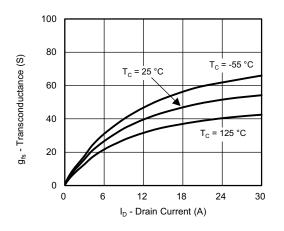
2



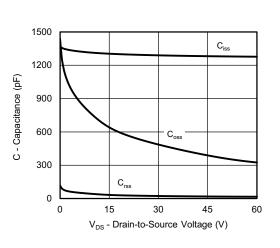
TYPICAL CHARACTERISTICS ($T_A = 25 \text{ °C}$, unless otherwise noted)



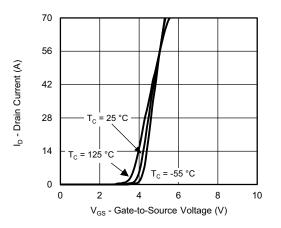
Output Characteristics



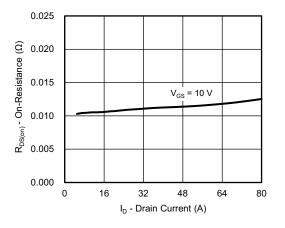
Transconductance



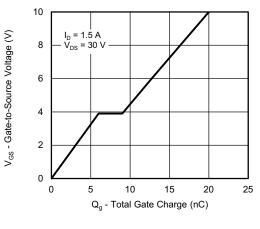
Capacitance



Transfer Characteristics



On-Resistance vs. Drain Current



Gate Charge

S22-0060-Rev. B, 24-Jan-2022

3

Document Number: 76110

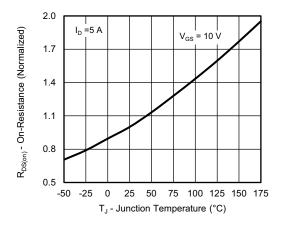
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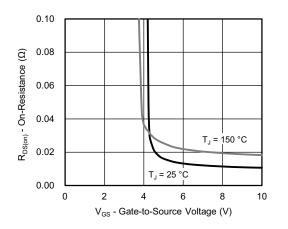
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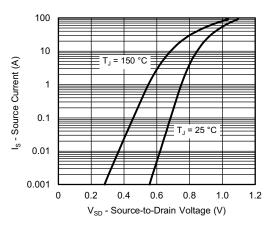
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



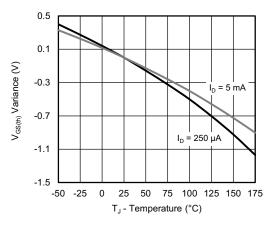
On-Resistance vs. Junction Temperature



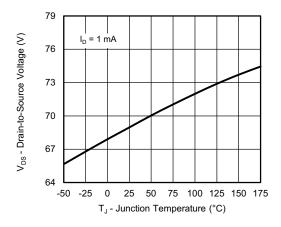
On-Resistance vs. Gate-to-Source Voltage



Source Drain Diode Forward Voltage



Threshold Voltage

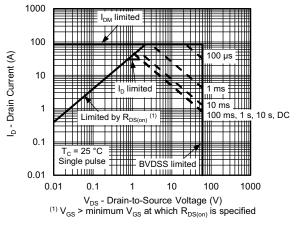


Drain Source Breakdown vs. Junction Temperature

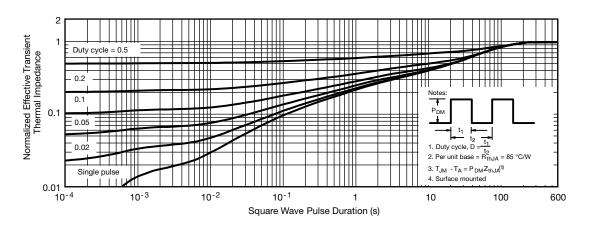
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THERMAL RATINGS ($T_A = 25 \text{ °C}$, unless otherwise noted)



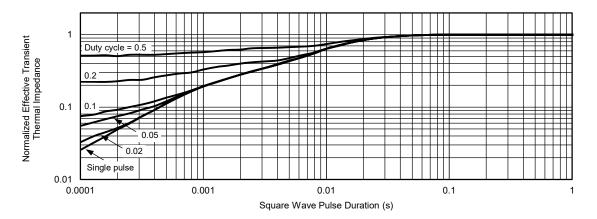
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Case (25 °C)

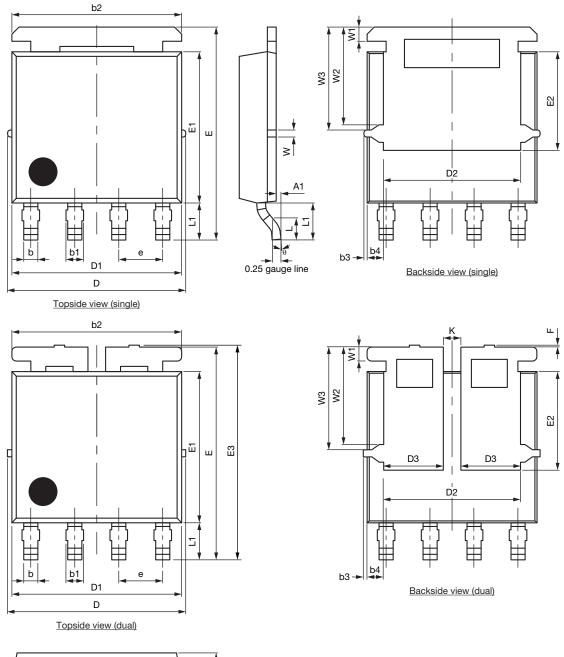
are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

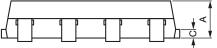
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6









Package Information



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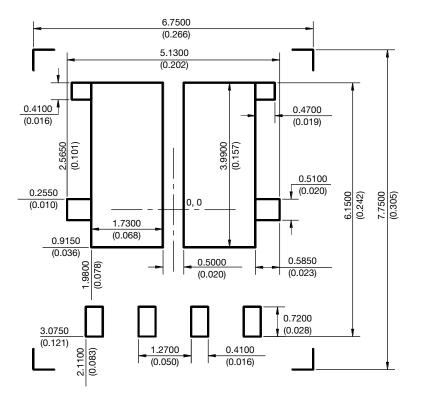
DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX	
А	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
E	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
E3	6.05	6.22	6.40	0.238	0.245	0.252	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
К		0.51		0.020			
W		0.23		0.009			
W1		0.41			0.016		
W2		2.82			0.111		
W3		2.96		0.117			
θ	0°	-	10°	0°	-	10°	

Note

• Millimeters will govern



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L DUAL



Recommended Minimum Pads Dimensions in mm (inches) Keep-out 6.75 (0.266) x 7.75 (0.305)

Revision: 07-Feb-12



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1